

Henkel Solutions for Laminate Packaging Solder Pastes

PRODUCT DESCRIPTION KEY ATTRIBUTES ALLOY PARTICLE SIZE DISTRIBUTION VISCOSITY AT 25°C (cP) ATMOSPHERE CLASSIFICATION LIFE
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Dispensable

LOCTITE HF 250DP	+ Low voiding - Exceptional dot-to-dot consistency - High-speed dispense capability with zero slump - Colorless residues	SAC387	Type 5	160,000 at 5 rpm	Nitrogen	ROLO	12 months up to -18°C	
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Printable

LOCTITE GC 10	Temperature- stable, halogen- free, Pb-free, no-clean solder paste	Low voiding Exceptionally long stencil life and abandon time Outstanding paste transfer efficiency Excellent wetting and coalescence in air Suitable for high density, small to large boards	SAC305	Type 3, 4, 4.5 (4A) and 5	900,000 – 933,000 at 5 rpm	Designed for air; suitable with nitrogen	ROLO	12 months up to 26.5°C
LOCTITE HF 212	Halogen-free, Pb-free, no-clean solder paste	Low voiding Extended stencil life and abandon time Printing, pin-in-paste and enclosed head print capability Excellent wetting and fine pitch coalescence Suitable for medium to large boards	90iSC 96S SAC0307 SAC305 SAC387	Type 3, 4, 4.5 (4A) and 5	750,000 – 900,000 at 5 rpm	Air and nitrogen	ROLO	6 months at 0°C – 10°C

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